TOSHIBA FIELD EFFECT TRANSISTOR SILICON P CHANNEL MOS TYPE (U-MOSIII)

TPC8109



LITHIUM ION BATTEERY POREABLE MACHINES AND TOOLS NOTE BOOK PC

·Compact and thin package, and a small mounting area

·Low drain-source ON resistance $:R_{DS(ON)}= 14 \text{ m} \Omega \text{ (typ.)}$

·High forward transfer admittance : $|Y_{fs}|$ = 19 S(typ.)

·Low leakage current

 $I_{DSS} = -10 \,\mu \,A(max.)(V_{DS} = -30V)$

·Enhancement mode

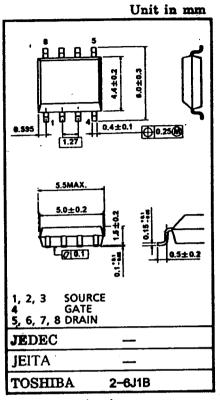
 $V_{th} = -0.8 \sim -2.0 \text{V} (V_{DS} = -10 \text{V}, I_{D} = -1 \text{mA})$

Maximum Ratings (T_a=25°C)

Char	acteristics	Symbol	Rating	Unit		
Drain-source volta	V _{DSS}	-30	٧			
Drain-gate voltage	V _{DGR}	-30	٧			
Gate-source volta	V _{GSS}	±20	٧			
Drain current	DC	(Note 1)		-10	Α	
	Pulse	(Note 1)	I _{DP}	-40		
Drain power dissip	P₀	1.9	W			
Drain power dissip	ation(t=10s)	P₀	1.0	VV.		
Single pulse avalar	E _{AS}	130	mJ			
Avalanche current	Avalanche current			-10	Α	
Repetitive avalanche energy (Note 2a)(Note 4)			E _{AR}	0.19	mJ	
Channel temperature			T _{ch}	150	°C	
Storage temperature range			T_{stg}	-55∼150	°C	

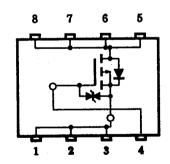
Note:(Note 1),(Note 2),(Note 3),(Note 4) Please see next page.

This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.080g(typ.)

CIRCUIT CONFIGURATION

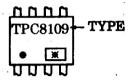


Thermal Characteristics

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Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t=10s) (Note 2a)	$R_{th(ch-a)}$	65.8	°C/W
Thermal resistance, channel to ambient (t=10s) (Note 2b)	$R_{th(ch-a)}$	125	°C/W

Marking(Note 5)



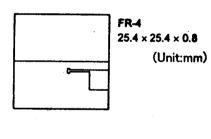
Note 1:Please use devices on condition that the channel temperature is below 150°C.

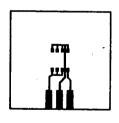
Note 2:

a)Device mounted on a glass-epoxy board(a)

(a)

b)Device mounted on glass-epoxy board(b)





(b)

FR-4 25.4 × 25.4 × 0.8 (Unit:mm)

Note $3:V_{DD}=-24V$, $T_{ch}=25$ °C(initial), L=1.0mH, $R_{G}=25\Omega$, $I_{AR}=-10$ A

Note 4:Reptitve rating; pulse width limited by max channel temperature.

Note 5: ● on lower left of the marking indicates Pin 1.

* shows Lot number .(Year of manufacture: last decimal digit of the year of manufacture, Month of manufacture : January to December are denoted by letters A to L respectively)

Electrical Characteristics (T_a=25°C)

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Charact	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cui	rrent	I _{GSS}	$V_{GS} = \pm 16V, V_{DS} = 0V$	_	-	±10	μΑ
Drain cut-OFF o	urrent	I _{DSS}	V _{DS} =-30V,V _{GS} =0V	-	-	-10	μА
Drain-source breakdown voltage		V _{(BR)DSS}	I _D =-10mA,V _{GS} =0V	-30	_	-	
		V _{(BR)DSX}	I _D =-10mA,V _{GS} =20V	-15	-	_	V
Gate threshold v	oltage/	V _{th}	V _{DS} =-10V,I _D =-1mA	-0.8	_	-2.0	٧
Drain-source ON resistance		В	V _{GS} =-4V,I _D =-5A	_	24	30	mΩ
		R _{DS(ON)}	V _{GS} =-10V,I _D =-5A		14	20	
Forward transfer admittance		Y _{fs}	V _{DS} =-10V,I _D =-5A	9	19	_	s
Input capacitance		C _{iss}	V _{DS} =-10V,V _{GS} =0V,f=1MHz	-	2260	_	pF
Reverse transfer capacitance		C_{rss}		_	290	_	
Output capacitance		Coss		-	350	-	1
	Rise time	t,	V _{GS} -10V I _D = -5A V _{OUT} R _L = 3Ω V _{DD} = -15V V _{DD} = -15V V _{DD} = 15V V _{DD} = 10 μs	-	5	_	
	Turn-ON time	t _{on}		-	13	_	ns
Switching time	Fall time	t _f		_	34	_	
	Turn-OFF time	t _{off}		_	143	_	
Total gate charge (gate-source plus gate-drain)		Q _e	$V_{DD} = -24V, V_{GS} = -10V, I_D = -10A$		45	_	
Gate-source charge 1		Q_{gs1}		-	6.5	_	nC
Gate-Drain("mill	Gate-Drain("miller")charge			_	10	-	

Source-Drain Diode Ratings and Characteristics (T_a =25°C)

Characterist	ics	Symbol	Test Condition	M in	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	-	-	-	-40	Α
Diode foward voltage		V _{DSF}	I _{DR} =-10A,V _{GS} =0V	_	_	1.2	٧

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RESTRICTIONS ON PRODUCT USE

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